

DATA SHEET

SURFACE MOUNT MULTILAYER CERAMIC CAPACITORS

General purpose class II X6S

> 4 ∨ TO 50 ∨ I00 pF to 47μF

RoHS compliant & Halogen free



YAGEO Phícomp

<u>SCOPE</u>

This specification describes X6S series chip capacitors with lead-free terminations.

APPLICATIONS

PCs, Hard disk, Game PCs Power supplies DVD players Mobile phones Data processing

<u>FEATURES</u>

Supplied in tape on reel Nickel-barrier end termination RoHS compliant Halogen free compliant

ORDERING INFORMATION-GLOBAL PART NUMBER,

All part numbers are identified by the series, size, tolerance, TC material, packing style, voltage, process code, termination and capacitance value.

YAGEO BRAND ordering code GLOBAL PART NUMBER (PREFERRED)

СС	<u>xxxx</u>	<u>x</u>	<u>x</u>	X6S	<u>x</u>	BB	<u>xxx</u>
	(1)	(2)	(3)		(4)		(5)

(I) SIZE - INCH BASED (METRIC)

0201 (0603)
0402 (1005)
0603 (1608)
0805 (2012)
1206 (3216)
1210 (3225)

(2) TOLERANCE

 $K = \pm 10\%$

 $M = \pm 20\%$

(3) PACKING STYLE

- R = Paper/PE taping reel; Reel 7 inch
- K = Blister taping reel; Reel 7 inch
- P = Paper/PE taping reel; Reel 13 inch
- F = Blister taping reel; Reel 13 inch
- C = Bulk case

(4) RATED VOLTAGE

- $4 = 4 \vee$
- 5 = 6.3 V
- $6 = 10 \vee$
- 7 = 16 V
- 8 = 25 V
- 9 = 50 V

(5) CAPACITANCE VALUE

2 significant digits+number of zeros

The 3rd digit signifies the multiplying factor, and letter R is decimal point

Example: $103 = 10 \times 10^3 = 10,000 \text{ pF} = 10 \text{ nF}$

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handbook, 4 columns

electrodes

ceramic material

-Fig. I Surface mount multilayer ceramic capacitor construction

CONSTRUCTION

The capacitor consists of a rectangular block of ceramic dielectric in which a number of interleaved metal electrodes are contained. This structure gives rise to a high capacitance per unit volume.

The inner electrodes are connected to the two end terminations and finally covered with a layer of plated tin (NiSn). Thterminations are lead-free. A cross section of the structure is shown in Fig.1.

Table I For outlines see fig. 2



TYPE	L _I (mm)	W (mm)	T (MM)	L ₂ / L ₃ min.	(mm) max.	L ₄ (mm) min.
0201	0.6 ±0.03	0.3 ±0.03	0.3 ±0.03	0.10	0.20	0.20
0201	0.6±0.09	0.3 ±0.09	0.3±0.09	0.10	0.20	0.20
	1.0 ±0.05	0.5 ±0.05	0.5 ±0.05			
0402	1.0 ±0.15	0.5 ±0.15	0.5 ±0.15	0.15	0.35	0.40
	1.0 ±0.20	0.5 ±0.20	0.5 ±0.20			
	1.6±0.10	0.8 ±0.10	0.8 ±0.10			
0603	1.6 ±0.15	0.8 ±0.15	0.8 ±0.15	0.20	0.60	0.40
	1.6 ±0.20	0.8 ±0.20	0.8 ±0.20			
0805	2.0±0.20	1.25 ±0.20	1.25 ±0.20	0.25	0.75	0.55
1206	3.2 ±0.30	1.6 ±0.20	1.6 ±0.20	0.25	0.75	1.40
1210	3.2 ±0.40	2.5 ±0.30	2.5 ±0.20	0.25	0.75	1.40
1210	3.2 ±0.40	2.5 ±0.30	2.5 ±0.30	0.25	0.75	1.40

OUTLINES

terminations



MLB457

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CAPACITANCE RANGE & THICKNESS FOR X65

Table 2 Sizes from 0201 to 0603

CAP.	0201				0402				0603					
	6.3V	10V	16V	25V	6.3 V	10 V	16 V	25 V	4 V	6.3 V	10 V	16 V	25 V	50 V
100 nF	0.3±0.03 (0.3±0.03												
220 nF					0.5±0.05	0.5±0.05	0.5±0.05	0.5±0.05						
470 nF					0.5±0.05	0.5±0.05								
ΙuF					0.5±0.05	0.5±0.05			0.8±0.1	0.8±0.1	0.8±0.1	0.8±0.1	0.8±0.1	
2.2 uF					0.5±0.20	0.5±0.20			0.8±0.1	0.8±0.1	0.8±0.1	0.8±0.2		
4.7 uF					0.5±0.15				0.8±0.2	0.8±0.2				
I0 uF									0.8±0.2	0.8±0.2				
22 uF									0.8±0.2	0.8±0.2				
47 uF														

Table 3	Sizes from	0805 to	1210
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CAP.	0805					1206				1210		
	6.3 V	10 V	16 V	25 V	50 V	6.3 V	10 V	16 V	25 V	6.3 V	10 V	16V
100 nF												
220 nF												
470 nF												
l uF												
2.2 uF	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2							
4.7 uF	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2								
I0 uF	1.25±0.2	1.25±0.2	1.25±0.2			1.6±0.2	1.6±0.2	1.6±0.2	1.6±0.2			
22 uF	1.25±0.2					1.6±0.2	1.6±0.2	1.6±0.2				
47 uF										2.5±0.2	2.5±0.2	
100 uF												

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THICKNESS CLASSES AND PACKING QUANTITY

Table 4	ļ						
SIZE	THICKNESS	TAPE WIDTH -	Ø180 MM	1 / 7 INCH	Ø330 MM	1/13 INCH	QUANTITY
CODE	CLASSIFICATION	QUANTITY PER REEL	Paper	Blister	Paper	Blister	PER BULK CASE
0201	0.3 ±0.03 mm	8 mm	15,000		50,000		
0402	0.5 ±0.05 mm	8 mm	10,000		50,000		50,000
0603	0.8 ±0.1 mm	8 mm	4,000		15,000		15,000
0805	1.25 ±0.2 mm	8 mm		3,000		10,000	5,000
1206	1.6 ±0.2 mm	8 mm		2,000		8,000	
1210	2.5±0.2/0.3 mm	8 mm		500			

ELECTRICAL CHARACTERISTICS

X6S DIELECTRIC CAPACITORS; NISN TERMINATIONS

Unless otherwise specified, all tests and measurements shall be made under standard atmospheric conditions for testing as given in 5.3 of IEC 60068-1:

- Temperature: 15 $^\circ\text{C}$ to 35 $^\circ\text{C}$
- Relative humidity: 25% to 75%
- Air pressure: 86 kPa to 106 kPa

Before the measurements are made, the capacitor shall be stored at the measuring temperature for a time sufficient to allow the entire capacitor to reach this temperature.

The period as prescribed for recovery at the end of a test is normally sufficient for this purpose.

Table 5

DESCRIPTION	VALUE
Capacitance range	100 nF to 100 μF
Capacitance tolerance	±10% and ±20%
Dissipation factor (D.F.)	≤10%
Insulation resistance after 1 minute at U _r (DC)	Rins × Cr ≥ 100 / 50 Ω.F *
Maximum capacitance change as a function of temperature (temperature characteristic/coefficient):	±22%
Operating temperature range:	−55 °C to +105 °C

Note:

Rins × Cr ≥ 100 Ω.F	Rins × Cr ≥ 50 Ω.F
0201: 100nF to 470nF	0201: luF
0603: IuF, 2.2uF/ 6.3V to I6V, 4.7uF/ 6.3V to I6V 0805: 2.2uF, 4.7uF to I0uF/ 6.3V to I6V I206: I0uF/ 6.3V to I6V, 22uF/ 6.3V to I0V	0402: 220nF/ 6.3V to 25V, 470nF/ 6.3V to 10V, IuF to 2.2uF/ 6.3V to 10V, 4.7uF/ 6.3V 0603: 2.2uF/ 25V, 4.7uF/ 25V, 10uF to 22uF 0805: 4.7uF/ 50V, 10uF/ 25V, 22uF to 47uF
	1206: 10uF/ 25V, 22uF/ 16V, 47uF to 100uF 1210: 47uE to 100uF

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SOLDERING RECOMMENDATION

Table 6					
SOLDERING METHOD	SIZE ≤ 0402	0603	0805	1206	≥ 1210
Reflow	Reflow only	≥ 1.0 µF	≥ 2.2 µF	≥ 4.7 µF	Reflow only
Reflow/Wave		< 1.0 µF	< 2.2 µF	< 4.7 µF	

TESTS AND REQUIREMENTS

Table 7 Test procedures and requirements

TEST	TEST MET	HOD	PROCEDURE	REQUIREMENTS
Mounting	IEC 60384- 21/22	4.3	The capacitors may be mounted on printed-circuit boards or ceramic substrates	No visible damage
Visual Inspection and Dimension Check		4.4	Any applicable method using × 10 magnification	In accordance with specification
Capacitance ⁽¹⁾		4.5.1	Class 2: At 20 °C, 24 hrs after annealing Cap \leq 1 µF, f = 1 KHz, measuring at voltage 1 Vrms at 20 °C Cap > 1 µF, f = 1 KHz for C \leq 10 µF, rated voltage > 6.3 V, measuring at voltage 1 Vrms at 20 °C f = 1 KHz, for C \leq 10 µF, rated voltage \leq 6.3 V, measuring at voltage 0.5 to 1 Vrms at 20 °C f = 120 Hz for C > 10 µF, measuring at voltage 0.5 Vrms at 20 °C	Within specified tolerance
Dissipation 4.5.2 Factor (D.F.) ⁽¹⁾		4.5.2	Class 2: At 20 °C, 24 hrs after annealing Cap \leq 1 µF, f = 1 KHz, measuring at voltage 1 Vrms at 20 °C Cap $>$ 1 µF, f = 1 KHz for C \leq 10 µF, rated voltage $>$ 6.3 V, measuring at voltage 1 Vrms at 20 °C f = 1 KHz, for C \leq 10 µF, rated voltage \leq 6.3 V, measuring at voltage 0.5 Vrms at 20 °C f = 120 Hz for C $>$ 10 µF, measuring at voltage 0.5 Vrms at 20 °C	In accordance with specification
Insulation Resistance		4.5.3	At U _r (DC) for 1 minute	In accordance with specification

NOTE

I. The figure indicates typical inspection. Please refer to individual specifications.

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TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature Characteristic		Capacitance shall be measured by the steps shown in the following table. The capacitance change should be measured after 5 min at	Class I : Δ C/C: ±30ppm Class2:
		each specified temperature stage. Step Temperature(°C) a 25±2 b Lower temperature±3°C c 25±2 d Upper Temperature±2°C e 25±2 (1) Class I Temperature Coefficient shall be calculated from the formula as below Temp, Coefficient = $\frac{C2 - CI}{CI \times \Delta T} \times 10^{6}$ [ppm/°C] C1: Capacitance at step c C2: Capacitance at 125°C ΔT : 100°C(=125°C-25°C)	X6S: Δ C/C: ±22%
		 AT: 100°C(=125°C-25°C) (2) Class II Capacitance Change shall be calculated from the formula as below 	

 $\Delta C = \frac{C2 - CI}{CI} \times 100\%$

C1: Capacitance at step c C2: Capacitance at step b or d

			C2. Capacitance at step b or d	
Adhesion		4.7	A force applied for 10 seconds to the line joining the terminations and in a plane parallel to the substrate	Force size ≥ 0603: 5N size = 0402: 2.5N size = 0201: 1N
Bending Strength	IEC 60384- 21/22	4.8	Mounting in accordance with IEC 60384-22 paragraph 4.3	No visible damage
			Conditions: bending I mm at a rate of I mm/s, radius jig 5 mm	ΔC/C Class2: X6S: ±10%

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Surface Mount Multilayer Ceramic Capacitors General Purpose

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TEST	TEST METH	OD	PROCEDURE	REQUIREMENTS
Resistance to Soldering Heat		4.9	Precondition: 150 +0/–10 °C for 1 hour, then keep for 24 ±1 hours at room temperature Preheating: for size ≤ 1206: 120 °C to 150 °C for 1	Dissolution of the end face plating shall not exceed 25% of the length of the edge concerned
			minute Preheating: for size >1206: 100 °C to 120 °C for 1 minute and 170 °C to 200 °C for 1 minute	ΔC/C Class2: X6S: ±10%
			Solder bath temperature: 260 ±5 °C Dipping time: 10 ±0.5 seconds Recovery time: 24 ±2 hours	D.F. within initial specified value R _{ins} within initial specified value
Solderability		4.10	Preheated the temperature of 80 °C to 140 °C and maintained for 30 seconds to 60 seconds.	The solder should cover over 95% of the critical area of each termination
			 Temperature: 235±5°C / Dipping time: 2 ±0.5 s Temperature: 245±5°C / Dipping time: 3 ±0.5 s (lead free) Depth of immersion: 10mm 	
Rapid Change of	IEC 60384- 21/22	4.11	Preconditioning; 150 +0/–10 °C for 1 hour, then keep for 24 \pm 1 hours at .	No visual damage
Temperature			room temperature	ΔC/C Class2:
			5 cycles with following detail: 30 minutes at lower category temperature 30 minutes at upper category temperature	X6S: ±15%
			Recovery time 24 ±2 hours	D.F. meet initial specified value R _{ins} meet initial specified value

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TEST	TEST METH	IOD	PROCEDURE	REQUIREMENTS	
Damp Heat with U _r Load		4.13	 Preconditioning, class 2 only: 150 +0/-10 °C /1 hour, then keep for 24 ±1 hour at room temp Initial measure: Spec: refer to initial spec C, D, IR Damp heat test: 500 ±12 hours at 40 ±2 °C; 90 to 95% R.H. 1.0 U_r applied Recovery: Class 2: 24 ±2 hours Final measure: C, D, IR P.S. If the capacitance value is less than the minimum value permitted, then after the other measurements have been made the capacitor shall be preconditioned according to <i>"IEC 60384 4.1"</i> and then the requirements shall be met. 	No visual damage after recovery $\Delta C/C$ Class2: $\pm 20\%$ D.F. Class2: $2 \times initial value max$ R_{ins} Class2: Rins $\times Cr \ge 5s$ whichever is less	
Endurance	IEC 60384- 21/22	4.14	 Preconditioning, class 2 only: 150 +0/-10 °C /1 hour, then keep for 24 ±1 hour - at room temp Initial measure: Spec: refer to initial spec C, D, IR Endurance test:: Temperature: X6S: 105 °C Specified stress voltage applied for 1,000 hours: Applied 1.5 × Ur. Applied 1 Ur: 0201: 1uF 0402: 4.7uF, 10uF 0603: 10uF, 22uF 0805: 10uF/ 25V, 22uF/ 16V Recovery time: 24 ±2 hours Final measure: C, D, IR P.S. If the capacitance value is less than the minimum value permitted, then after the other measurements have been made the capacitor shall be preconditioned according to "IEC 60384 4.1" and then the requirements shall be met. 	No visual damage $\Delta C/C$ Class 2: $\pm 20\%$ D.F. Class 2: 2 × initial value max R_{ins} Class 2: Rins x Cr ≥ 10s	
Voltage Proof	IEC 60384-1	4.6	Specified stress voltage applied for 1∼5 seconds Ur ≤ 100 V: series applied 2.5 Ur Charge/Discharge current is less than 50 mA	No breakdown or flashover	

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<u>REVISION HISTORY</u>

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 6	Jan. 20, 2021	-	- Product range updated
Version 5	Jun. 2, 2020	-	- Product range updated
Version 4	Aug 7, 2017	-	- 0402 Dimension update
Version 3	Jul 19, 2017	-	- Product range updated
Version 2	Feb. 20, 2017	-	- Dimension & capacitance update
Version I	Sep. 16, 2015	-	- Dimension & capacitance update
Version 0	Nov. 18, 2014	-	- New datasheet for general purpose High Cap X6S



Surface-Mount Ceramic Multilayer Capacitors

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